



## PRODUCT / PROCESS CHANGE NOTIFICATION

**APCN-000953**

**Date: FEB-07-2024**

### Change Details

**Part Number(s) Affected:**

1	GN3052-3EA5AM3E3	7	GN3358-3EF8AW3E3
2	GN3257-3EB9BA6E3	8	GN3358-3EF9AU2E3
3	GN3289-3ED7BC2E3	9	GN3361-3EJ3AY2E3
4	GN3357-3EB9AT6E3	10	GN3362-3EJ2AX2E3
5	GN3357-3EB9AW3E3	11	GN3368-3EC8AT6E3
6	GN3357-3ED9AW3E3		

**Customer Part Number(s) Affected:**  N/A

Description, Purpose and Effect of Change:

#### Advanced PCN Notification: Manufacturing Line Relocations

The purpose of this letter is to provide customers with advance notification of ongoing qualification for the manufacturing line relocations listed below. Semtech will send out the final PCN notification after completing the qualification, with an estimated completion date of April 30, 2024.

- 1) **Hisense, a Semtech supplier, plans to relocate its TO assembly manufacturing line from Jiangmen (JM) to Qingdao (QD) plant** in order to adapt to market and technology changes and provide customers with better products.
  - ROSA assembly will still remain at the JM plant.
- 2) **The barrel manufacturing line of HuiFuKang (HFK), a supplier to Hisense, will be relocated from Wanda to Chengdu plant** in order to ensure the normal production and delivery of materials.
- 3) **Compass, a supplier to Hisense, is going to relocate its flex manufacturing line from Hong Kong to a factory in China** by the end of the second quarter of this year.
  - The Hong Kong factory will cease operations.
  - The supplier is going to use the new name "Xiamen Compass Semiconductor Company Limited".

The production materials and process flow will remain unchanged for the three changes stated above.

Refer to the following pages for the following:

- Complete addresses of old and new locations of manufacturing lines.
- Equipment comparison between Hisense' current and new TO assembly manufacturing line.



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<b>Change Classification</b>	<input checked="" type="checkbox"/> Major <input type="checkbox"/> Minor	<b>Impact to Form, Fit, Function</b>	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
<b>Impact to Data Sheet</b>	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	<b>New Revision or Date</b>	<input checked="" type="checkbox"/> N/A
<b>Impact to Performance, Characteristics or Reliability:</b>			
<ul style="list-style-type: none"> <li>There is no impact to form, fit, function, performance, and characteristics.</li> <li>It is expected that there will be no impact on reliability. This will be confirmed by comprehensive reliability testing.</li> </ul>			
<b>Implementation Date</b>	<b>JUN-30-2024</b>	<b>Work Week</b>	<b>27</b>
<b>Last Time Ship (LTS)</b> Of unchanged product	<b>N/A</b>	<b>Affecting Lot No. / Serial No. (SN)</b>	<b>N/A</b>
<b>Sample Availability</b>	<b>Middle of March 2024</b> (2 weeks lead time upon request)	<b>Qualification Report Availability</b>	<b>To be included in the final PCN notification</b>
<b>Supporting Documents for Change Validation/Attachments:</b>			
<ul style="list-style-type: none"> <li>Semtech will send out final PCN notification after completing the qualification, with an estimated completion date of April 30, 2024.</li> </ul>			

• **Complete addresses of old and new locations of manufacturing lines:**

Supplier name	Current plant	New plant
Hisense	A Zone, No. 8 Hisense Road, Tangxia Town, Pengjiang District, Jiangmen City, Guangdong Province, China	No. 218, Qianwangang Road, Economic and Technological Development Zone, Qingdao, Shandong Province, China
HuiFuKang (HFK)	Building C, Wanda Industrial Zone, Shiyen Town, Baoan District, Shenzhen City, China	Chongzhou Chongyang County Street Chuangxinlu second section 500 (Chengdu Huifukang Industrial Park, China
Compass	5th Floor, Chiaphua Centre, 12 Siu Lek Yuen Road, Shatin, New Territories, Hong Kong	Xiamen Hai Cang Information Technology Industrial Park, Fujian Province, China



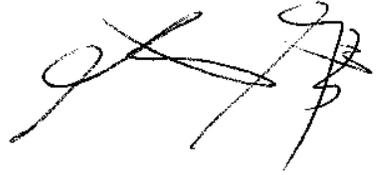
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**Equipment comparison between Hisense' current and new TO assembly manufacturing line**

<b>Process step</b>	<b>Current equipment Jiangmen (JM) plant</b>	<b>New equipment Qingdao (HD) plant</b>
Auto die bonding	AD819-21 & AD862	DA100M & AD862
High Temperature oven	JPO-91-200CP	HCOD-39-200
OGP Smart microscope	Smartscope ZIP Lite 250	Smartscope ZIP Lite 250
Auto wire bonding	Eagle60AP-LD	Eagle60AP-LD & Kaijo e20a
Pull force tester	Dage4000	Dage4000PXY & MFM1200
High Temperature oven	JPO-125-2000	IPO-125
Auto seam sealing machine	LA-1000 Baking condition: 110 mins @ 115°C	CS3-2.1 Baking condition: 3 hrs @ 150°C
Gross leak test	KYKY	FU-3
Fine leak test	Phoeni XL300	UL1000 Fab

<b>Quality Assurance</b>	
<b>Semtech Business Unit</b>	Signal Integrity Product Group
<b>Semtech Contact Info:</b>	<p>Pedro Jr. Bernas Staff Engineer, Product Quality Engineering pbernas@semtech.com (289) 856-9326 x 1162</p> 
<p><b>FOR FURTHER INFORMATION &amp; WORLDWIDE SALES COVERAGE:</b> <a href="http://www.semtech.com/contact/index.html#support">http://www.semtech.com/contact/index.html#support</a></p>	